



## Material Content Data Sheet



<b>Sales Product Name</b>				IPZ40N04S5L-4R8		<b>Issued</b>		25. January 2018	
<b>MA#</b>				MA001338258					
<b>Package</b>				PG-TSDSON-8-32		<b>Weight*</b>		35.35 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.336	0.95	0.95	9491	9491	
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		88		
	non noble metal	zinc	7440-66-6	0.012	0.04		352		
	non noble metal	iron	7439-89-6	0.249	0.70		7038		
wire	non noble metal	copper	7440-50-8	10.102	28.58	29.33	285758	293236	
	noble metal	gold	7440-57-5	0.030	0.09	0.09	861	861	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.11		1054	
encapsulation	plastics	epoxy resin	-	1.918	5.43		54255		
	inorganic material	silicondioxide	60676-86-0	16.667	47.12	52.66	471442	526751	
	leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11322	11322
plating	noble metal	silver	7440-22-4	0.086	0.24	0.24	2422	2422	
solder	noble metal	silver	7440-22-4	0.013	0.04		367		
	non noble metal	tin	7440-31-5	0.010	0.03		294		
	non noble metal	lead	7439-92-1	0.496	1.40	1.47	14035	14696	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		17		
	non noble metal	zinc	7440-66-6	0.002	0.01		66		
	non noble metal	iron	7439-89-6	0.047	0.13		1329		
heat sink CLIP	non noble metal	copper	7440-50-8	1.908	5.40	5.54	53960	55372	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
heat sink CLIP	non noble metal	iron	7439-89-6	0.073	0.21		2060		
	non noble metal	copper	7440-50-8	2.958	8.37	8.59	83660	85849	
	*deviation	< 10%				Sum in total:	100.00	1000000	

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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